

Appl. No. 10/828,993
Reply to Examiner's Action dated 11/29/2005

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-28 (Cancelled)

29. (Currently amended) A radio frequency (RF) component comprising:
a dielectric layer having opposing first and second major surfaces, the first surface being
free from a semiconductor substrate, said dielectric layer having a plurality of openings
extending between the first and second opposing major surfaces; and
a patterned conductive layer on the second major surface of said dielectric layer,
wherein the plurality of openings are on opposing sides of the patterned
conductive layer and through the RF component at least to the semiconductor substrate.

30. (Original) The RF component of Claiming 29 wherein said plurality of openings
are arranged in a predetermined pattern.

31. (Original) The RF component of Claim 30 wherein the predetermined pattern has
substantially uniform spacing between adjacent openings.

32. (Currently amended) The RF component of Claim 29 [[1]] wherein the
substantially uniform spacing is in a range of about 20 to about 200 μm [[μm]].

33. (Currently amended) The RF component of Claim 29 [[9]] wherein each opening
has a diameter in a range of about .5 to 2 0 μm [[μm]].

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34. (Currently amended) The RF component of Claim 29 [[119]] wherein each opening has respective rounded over edges adjacent the first and second major surfaces.

35. (Currently amended) The RF component of Claim 29 wherein the plurality of openings are laterally adjacent portions of the patterned conductive layer with no openings extending through the patterned conductive layer.